



Fogale Nanotech DEEPROBE 300-M

Serial NR: DPB-7DA-001

Vintage +/- 2014

[Contact? Click here](#)

Technology

Low Coherence IR interferometry for step high measurement

Applications

High A/R TSV depth measurement for 200 and 300mm wafer (Via first & Middle)

Benefits

Non-destructive Technology

Fast and easy to use

CCD camera for spot positioning and pattern recognition

Adjustable Metrology spot size

TSV diameter > 2um A:R up to 30

Calibration and maintenance free

